

WHAT IS CLAIMED IS:

Claim 1 (currently amended): A method for making an electric circuit board comprising the steps of:

providing a member having a central layer of a first material which is operatively contained between first and second layers of a second material;

placing a layer of a third material upon certain portions of said first layer, thereby exposing at least one portion of said first layer; [[and]]

placing a plurality of layers of said second material on top of said [[third]] layer of third material, effective to form a multi-layer circuit board having an aperture which extends through said formed circuit board and which terminates upon said exposed at least one portion of said first layer;

forming at least one slotted aperture through said central layer and through said first and second layers of a second material;

forming a sighting window within each of said plurality of layers of said second material and forming at least one sighting window within said layer of said third material, said at least one sighting window of said third material being visually aligned with said at least one slotted aperture, thereby allowing said third material to be operatively placed upon

predetermined portions of said first layer in a desired position.

Claim 2 (previously presented): The method of claim 1 wherein said second material comprises electrically conductive material.

Claim 3 (previously presented): The method of claim 2 wherein said second material comprises copper.

Claim 4 (previously presented): The method of claim 3 wherein said central layer of material comprises aluminum.

Claim 5 (previously presented): The method of claim 4 wherein said third material comprises a dielectric material.

Claim 6 (previously presented): The method of claim 1 further comprising the step of forming a registration slot within said member.

Claim 7 (canceled): The method of claim 6 further comprising the step of forming a sighting window within each of said plurality of layers of said second material and within said layer of said third material.

Claim 8 (previously presented): The method of claim 1 further comprising the step of selectively etching said central layer, effective to form at least one air-bridge.

Claim 9 (previously presented): The method of claim 1 further comprising the step of placing solder within said aperture.

Claim 10 (previously presented): The method of claim 1 further comprising the step of preventing said central layer from being

resident within said aperture.

Claim 11 (currently amended): A method for making a circuit board comprising the steps of:

providing a member having a central layer of a first material which is operatively positioned between top and bottom layers of a second material;

removing a portion of said ~~[[first]]~~ top and said ~~second~~ bottom layers, thereby exposing portions of said central layer of said first material;

providing a first layer of a dielectric material and placing said ~~provided~~ first layer of said dielectric material onto certain portions of said top layer, thereby overlaying said exposed portions of said central layer and creating first and second exposed portions of said top layer;

providing a third layer of said second material and placing said third layer onto said first layer of said dielectric material and over said first and second exposed portions of said top layer;

removing those portions of said third layer which overlay said first and said second exposed portions of said top layer;

providing a second layer of said dielectric material and placing said second layer of said dielectric material onto said third layer after those portions of said third layer which overlay said first and second exposed portions of said top layer

have been removed;

providing a fourth layer of said second material and placing said fourth layer upon said second layer of said dielectric material and over said first and second exposed portions of said top layer; and

removing those portions of said fourth layer which overlay said first and said second exposed portions of said top layer, thereby creating an electrical circuit board having a first aperture which extends through said third and fourth layers of said second material and through said first and second layers of said dielectric material while terminating within said first layer of said second material, and a second aperture which extends through said third and fourth layers of said second material and through said first and second layers of said dielectric material while terminating within said first layer of said second material.

Claim 12 (previously presented): The method of claim 11 wherein said first material comprises aluminum.

Claim 13 (previously presented): The method of claim 12 wherein said second material comprises copper.

Claim 14 (previously presented): The method of claim 11 wherein said first aperture is electrically grounded.

Claim 15 (previously presented): The method of claim 14 wherein

said second aperture is isolated from electrical ground.

Claim 16 (previously presented): The method of 11 further comprising the step of placing solder within said first and second apertures.

Claim 17 (previously presented): The method of claim 11 further comprising the step of forming a diving board over at least one of said first and second apertures.

Claim 18 (withdrawn): A circuit assembly made by the process of:

providing a core member having a central layer of a first material which is operatively contained between a top and a bottom layer of electrically conductive material;

creating an registration slot within said core member;

placing dielectric material on certain portions of said top layer, thereby exposing a first and a second portion of said top layer and creating a pre-circuit assembly; and

using said created registration slot to selectively add layers of electrically conductive material to said pre-circuit assembly, thereby creating a circuit assembly having a first aperture which is formed through said created circuit assembly and which terminates within said first exposed portion and having a second aperture which is formed through said created circuit assembly and which terminates within said second exposed portion.

Claim 19 (withdrawn): The circuit assembly of claim 18 wherein

an alignment slot is formed within each of said layers of electrically conductive material.

Claim 20 (withdrawn): The circuit assembly of claim 19 wherein solder is placed within each of said first and second apertures.